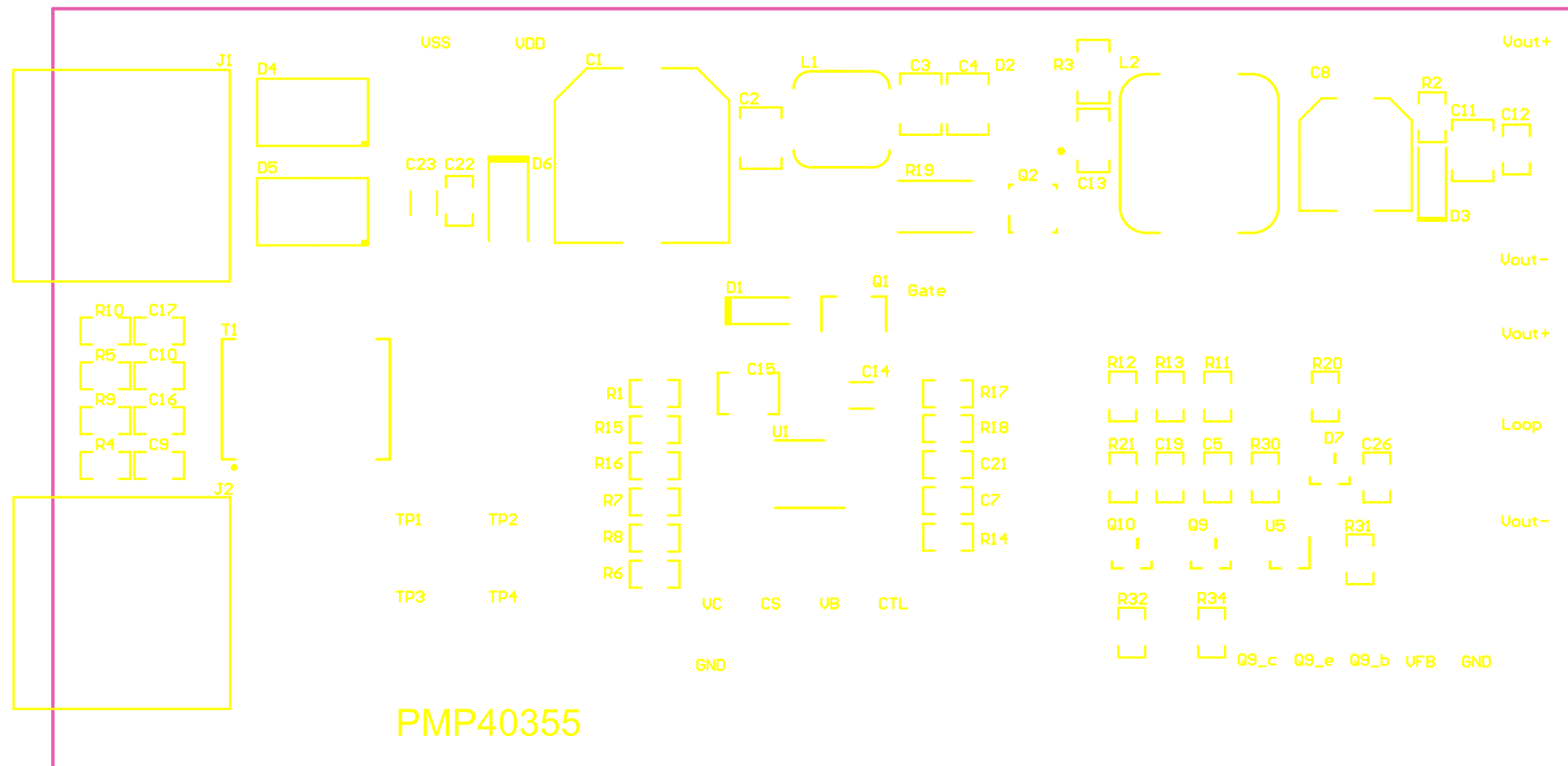
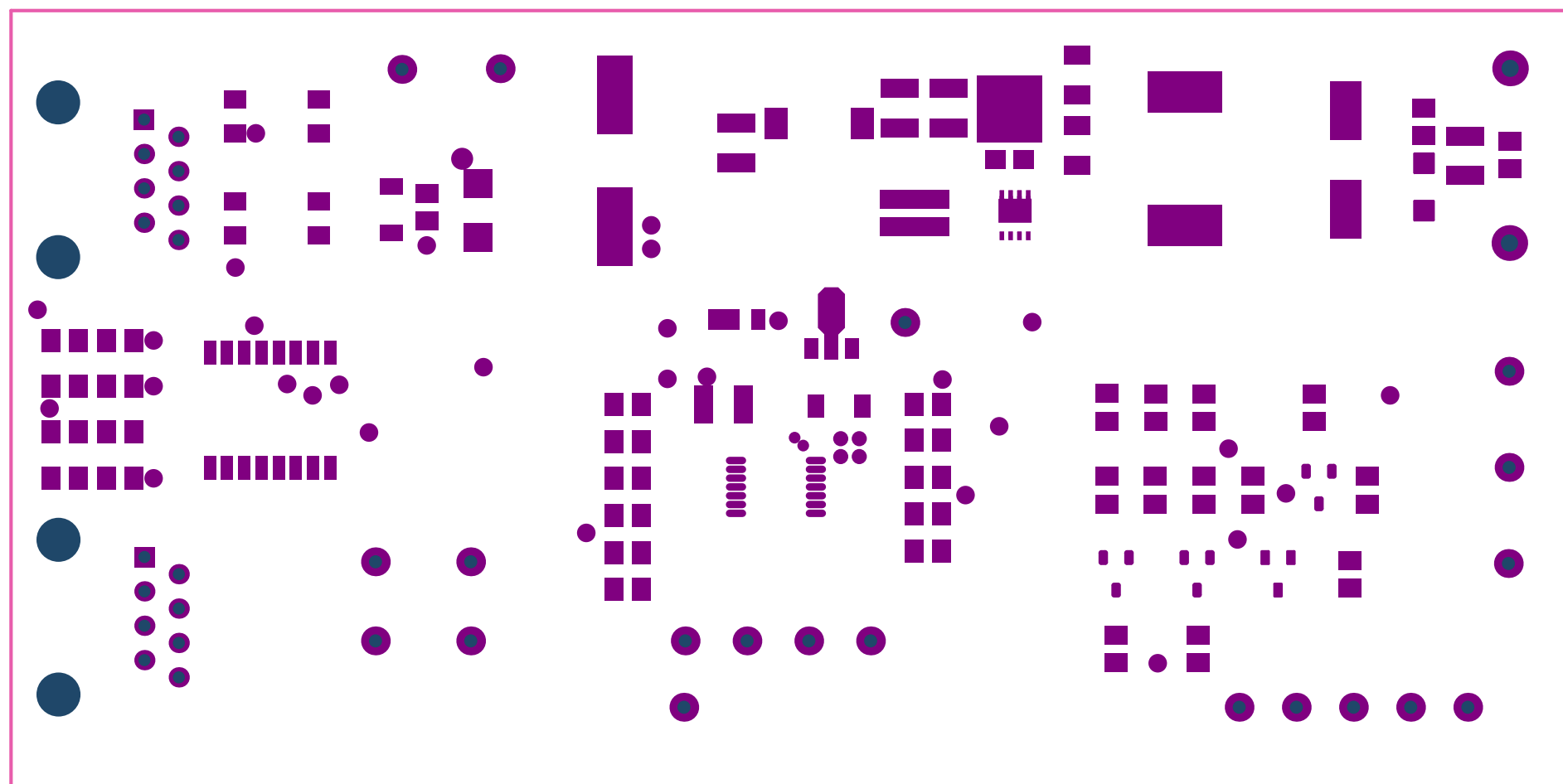


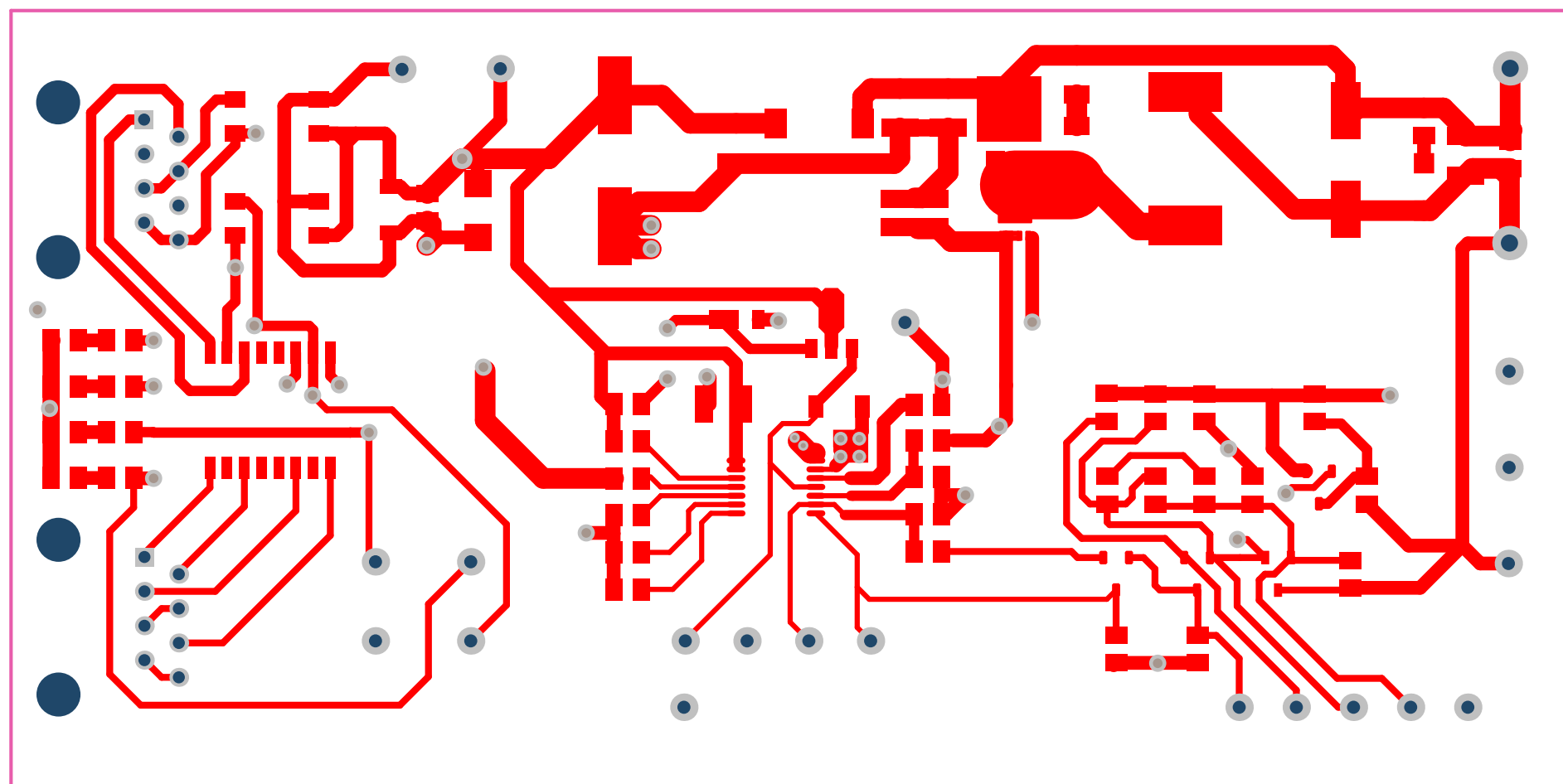
Drill Drawing Layer...they should be just to the right of your board shape



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40355	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 12/7/2017 3:52:31 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40355	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 12/7/2017 3:52:32 PM	TEXAS INSTRUMENTS	



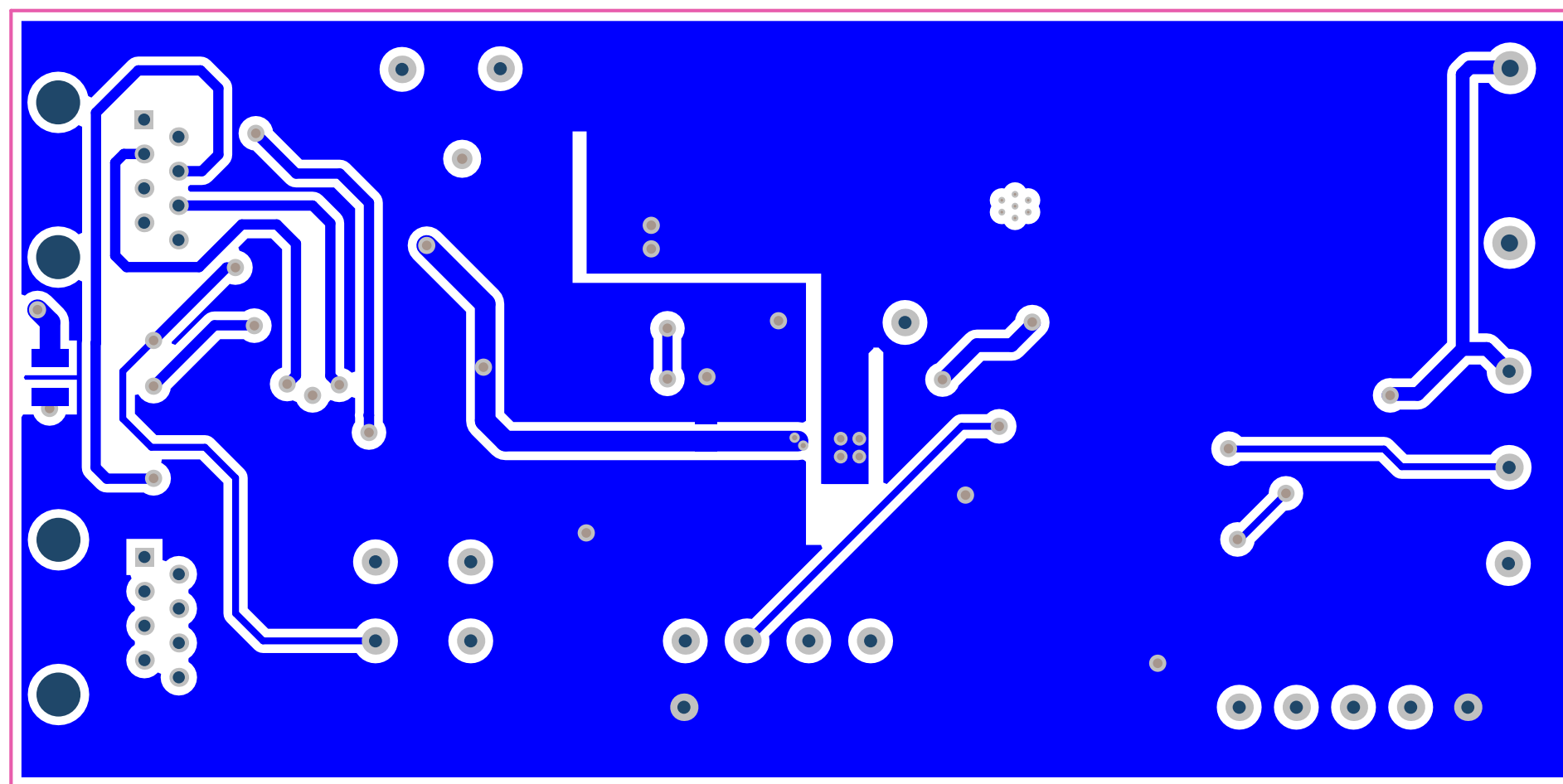
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40355	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 12/7/2017	3:52:33 PM	TEXAS INSTRUMENTS



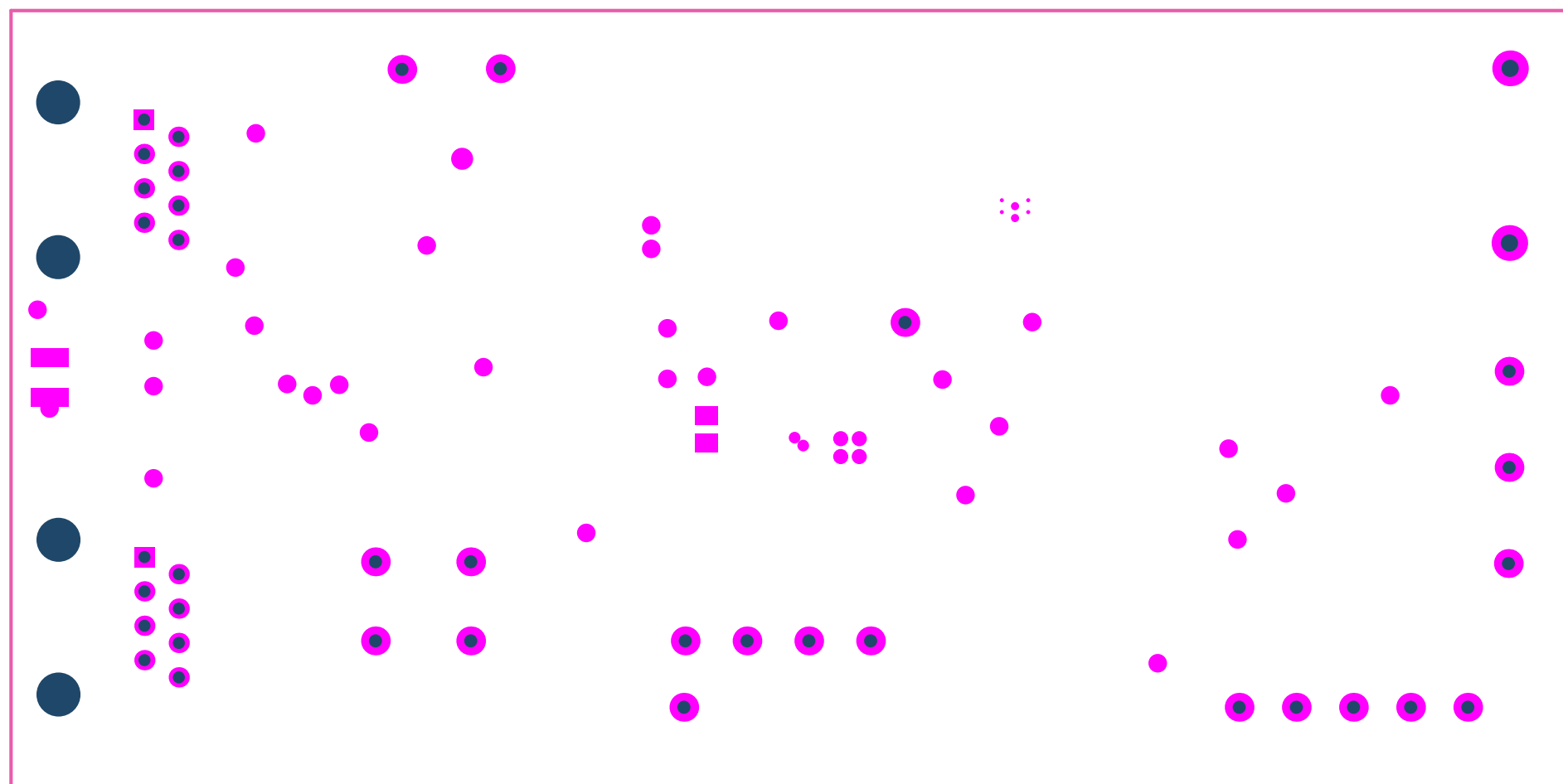
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40355	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 12/7/2017 3:52:33 PM		TEXAS INSTRUMENTS



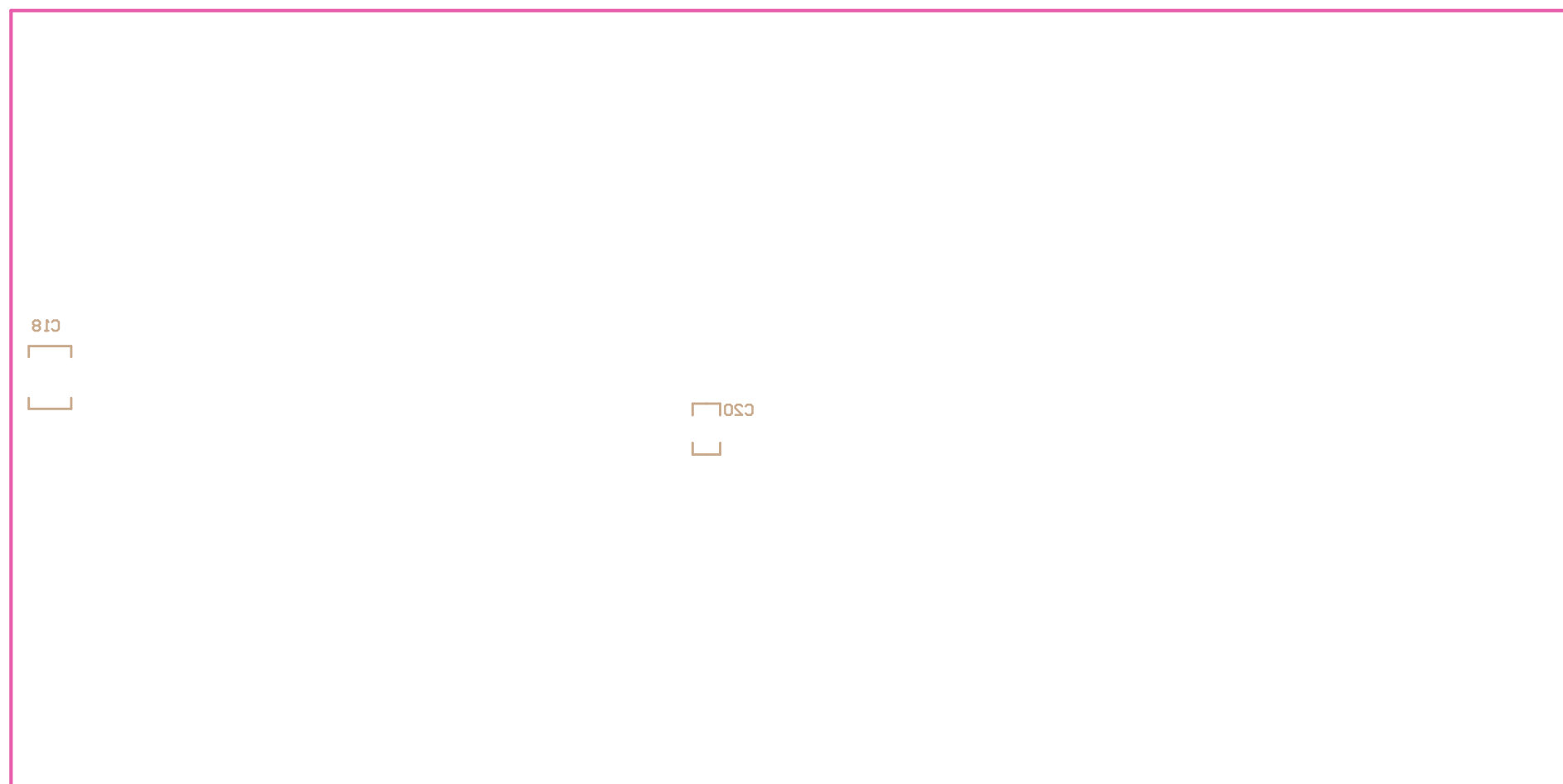
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40355	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 12/7/2017 3:52:34 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40355	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 12/7/2017 3:52:35 PM		TEXAS INSTRUMENTS



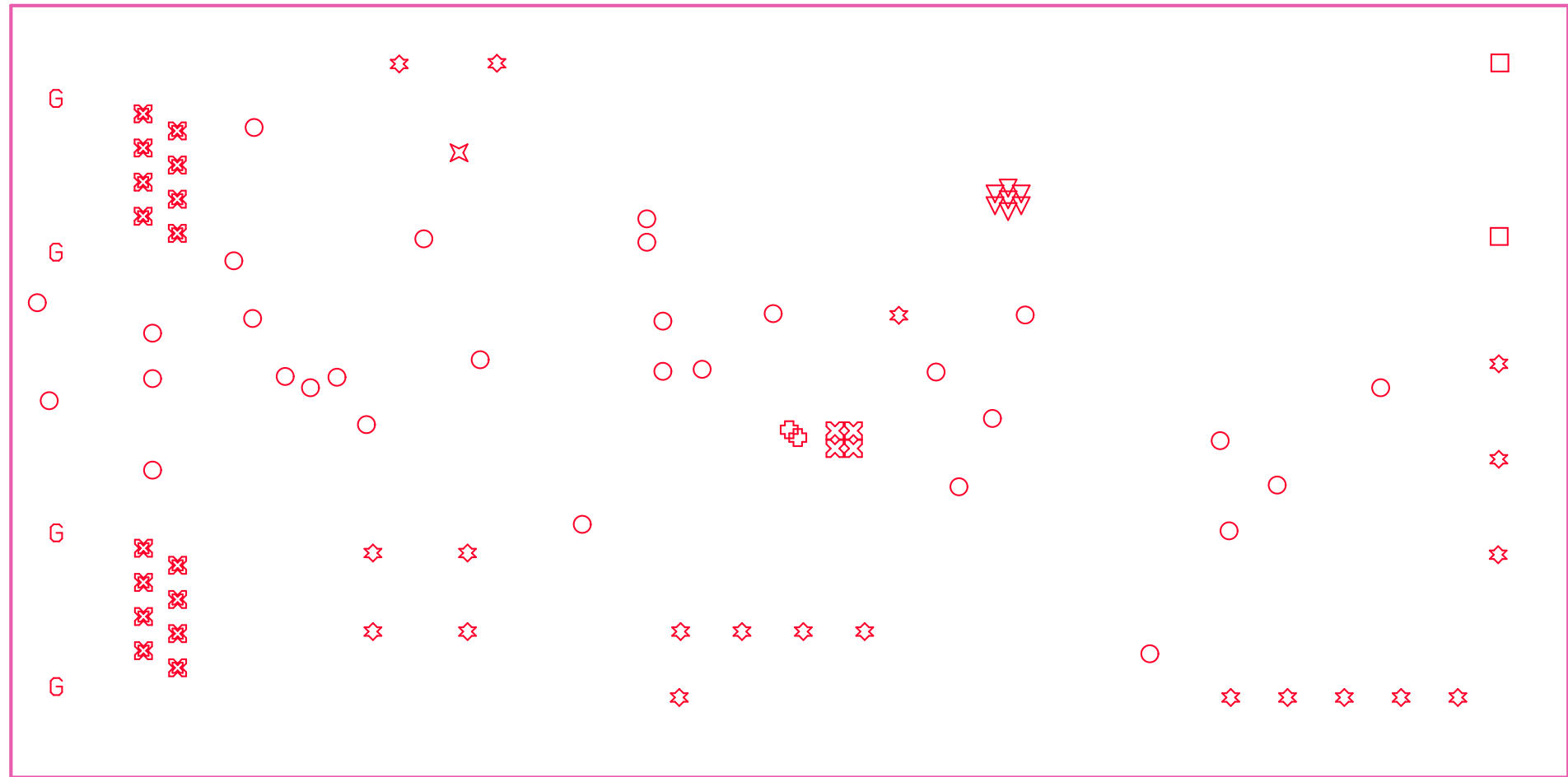
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40355	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/7/2017 3:52:36 PM	TEXAS INSTRUMENTS	



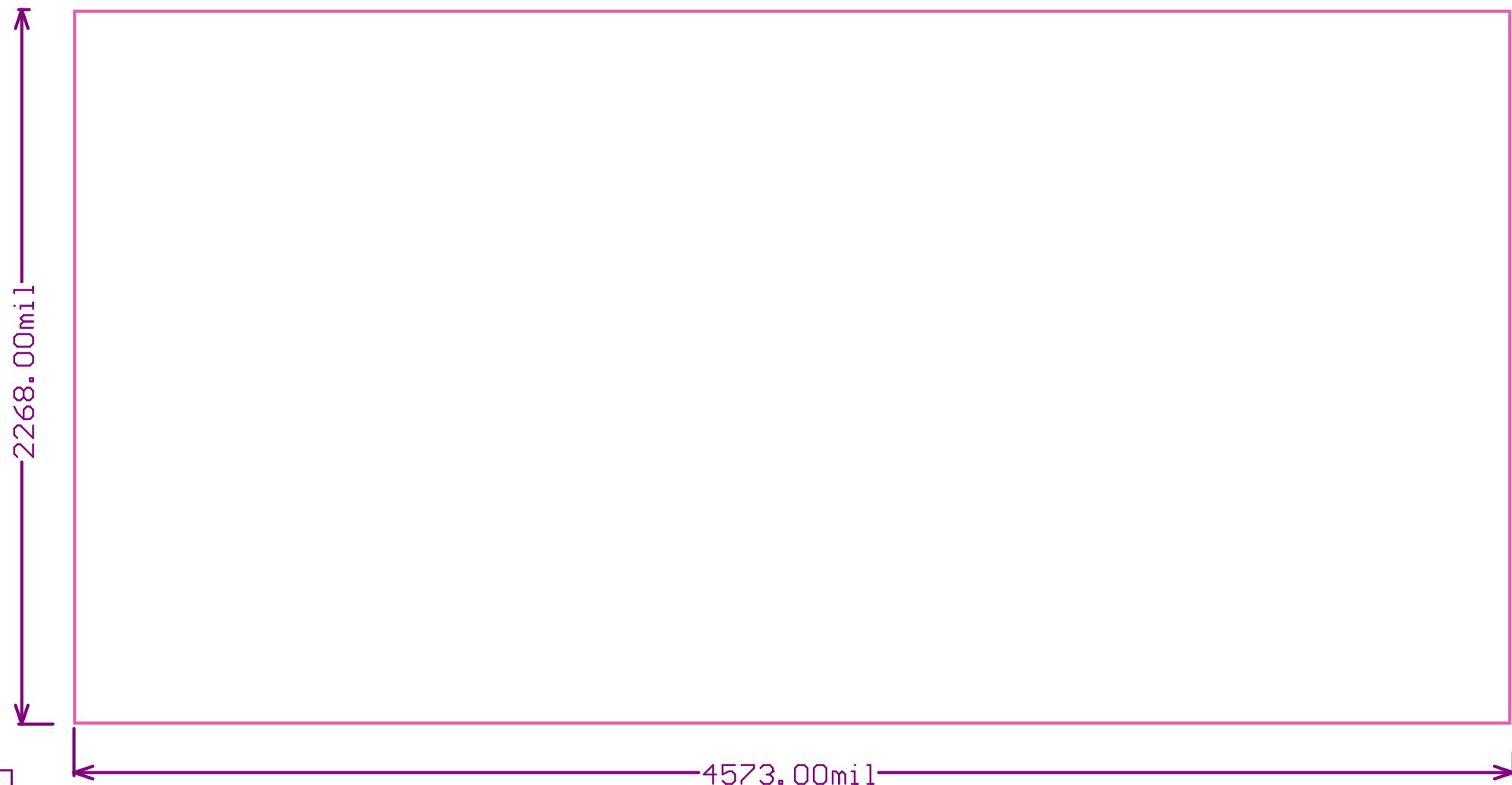
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40355	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 12/7/2017 3:52:37 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
G	4	128.00mil (3.251mm)	NPTH	Round	Top Layer - Bottom Layer	
▽	7	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	22.00mil (0.559mm)	PTH	Round	Top Layer - Bottom Layer	
○	30	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
✱	1	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	16	35.04mil (0.890mm)	PTH	Round	Top Layer - Bottom Layer	
☆	20	37.99mil (0.965mm)	PTH	Round	Top Layer - Bottom Layer	
□	2	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
	86 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40355	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 12/7/2017	3:52:37 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40355	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 12/7/2017 3:52:38 PM	TEXAS INSTRUMENTS	

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